

Title (en)

CONTACT-MAKING AND CONNECTION ARRANGEMENT ON THE BASIS OF FILM CONDUCTORS INTRODUCED IN A HOUSING

Title (de)

KONTAKTIERUNGS- UND VERBINDUNGSANORDNUNG AUF DER BASIS VON IN EINEM GEHÄUSE EINGEBRACHTEN FOLIENLEITERN

Title (fr)

SYSTÈME DE MISE EN CONTACT ET DE CONNEXION BASÉ SUR DES CONDUCTEURS À FEUILLE INSÉRÉS DANS UN BOÎTIER

Publication

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Application

**EP 11722341 A 20110429**

Priority

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Abstract (en)

[origin: WO2011135077A1] The invention relates to a contact-making and connection arrangement on the basis of film conductors introduced in a housing, wherein ends of the film conductors have a contact-making section and at least partly lie one above another. According to the invention, a double-sided self-adhesive or adhesive-coated conductive nonwoven material is situated between the contact-making sections facing one another, said material mechanically and electrically connecting the ends of the film conductors. Furthermore, the housing is embodied such that it is divided in the plane of the film conductors that have been introduced or are to be introduced, wherein the housing parts form half-shells and, in at least one half-shell, stamp-like projections are provided which lead to a deformation of the contact-making layer in such a way that a reduction of the electrical contact resistance of the connection occurs.

IPC 8 full level

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